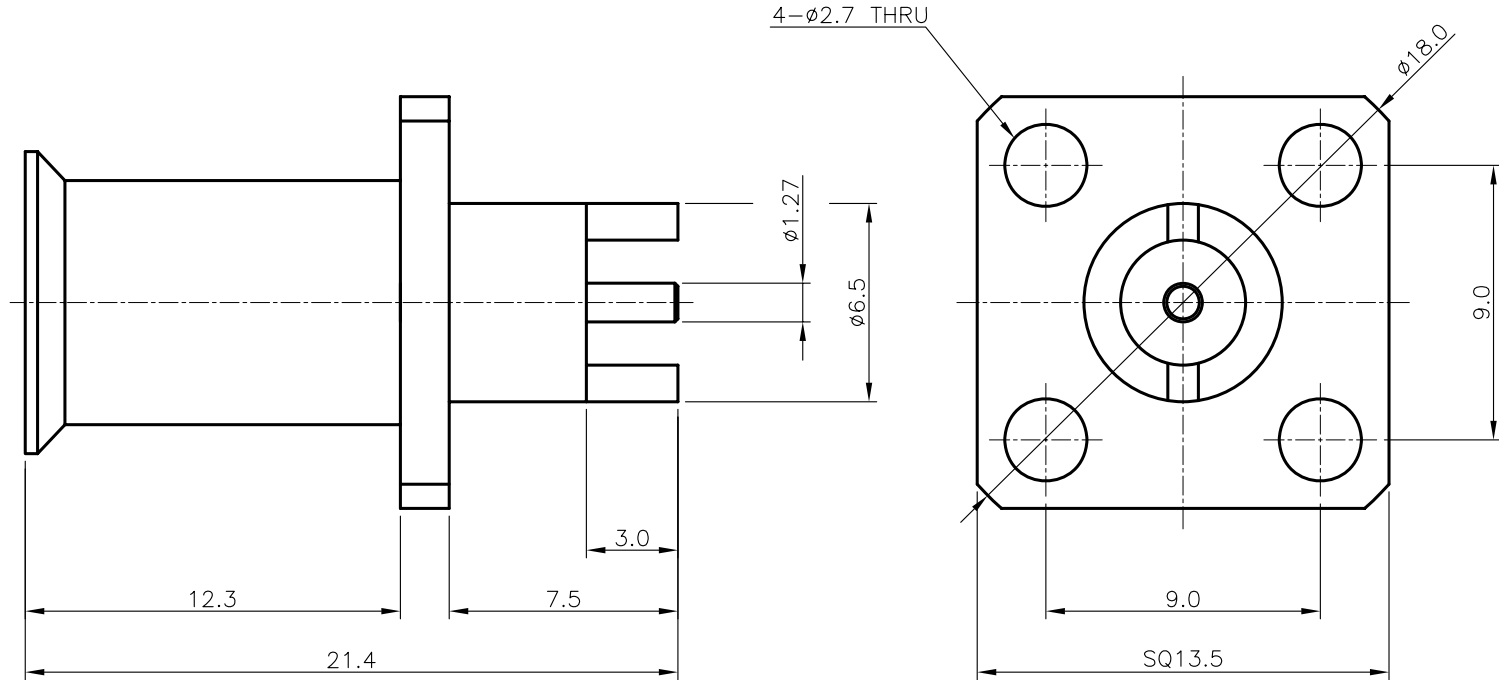


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	I.C.KIM		2018.10.12.
1	BMBC 공용화 치수 적용	S.Y.EUN	I.C.KIM	2018.11.27.
2	완제품 코드 변경	S.Y.EUN	I.C.KIM	2020.02.04.



- PIN 조립 시 상대물 PIN과 MATING 후 조립 할 것
- 상대물 PIN과 헐겁지 않고 적당한 텐션이 있을 것

3	INSULATOR	1	TEFLON		DIN03008-N/1
2	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT03968-5/2 DCT03968-5/1
1	BODY	1	MBsBD C3604BD-F	Nickel Plate	DBD04430-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2020. 02. 04.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		TITLE BMBC50 SOLDER END JS-4H-2R
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	4/1	DWG NO. CN03910-7/1 REVISION 2
		UNIT	mm	
				SHEET 1 of 1